# **MA27E02**

## Silicon epitaxial planar type

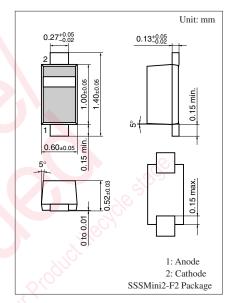
### For cellular phone

#### ■ Features

- High-frequency wave detection is possible.
- ullet Low forward voltage  $V_F$
- Small terminal capacitance C<sub>t</sub>

## ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Reverse voltage	$V_R$	20	V	
Maximum peak reverse voltage	$V_{RM}$	20	V	
Forward current	$I_{F}$	35	mA	
Peak forward current	$I_{FM}$	100	mA	
Junction temperature	$T_{j}$	125	°C	
Storage temperature	$T_{stg}$	-55 to +125	°C	

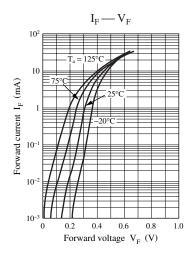


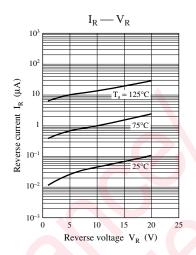
Marking Symbol: G

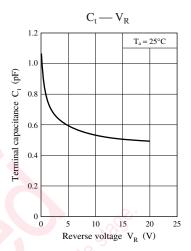
### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V <sub>F1</sub>	$I_F = 1 \text{ mA}$	00,	0,	0.40	V
	$V_{F2}$	$I_F = 35 \text{ mA}$		<i>&gt;</i>	1.0	V
Reverse current	$I_R$	$V_R = 15 \text{ V}$	200		200	nA
Terminal capacitance	C <sub>t</sub>	$V_R = 0 V, f = 1 MHz$			1.2	pF
Forward dynamic resistance	$r_{\mathrm{f}}$	$I_F = 5 \text{ mA}$		9		Ω

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
  - This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
  - 3. Rated input/output frequency: 2 GHz







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